

**ROCHESTER INSTITUTE OF TECHNOLOGY
MICROELECTRONIC ENGINEERING**

MEMS Resistor Laboratory

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Electrical and Microelectronic Engineering

Rochester Institute of Technology

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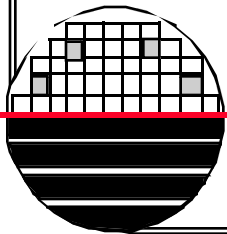
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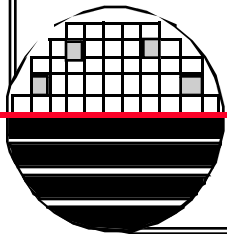
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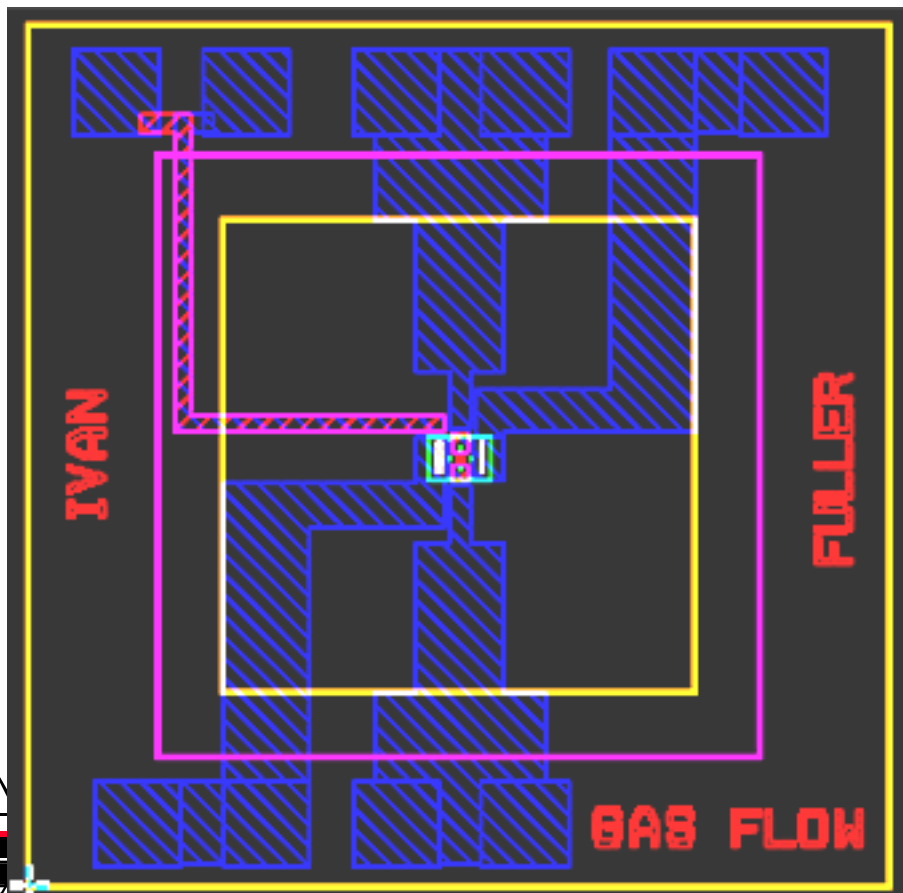
OUTLINE

Objective
Theory
Experimental Set Up
Measurements
Results
Discussion
References
Lab Instructors Notes



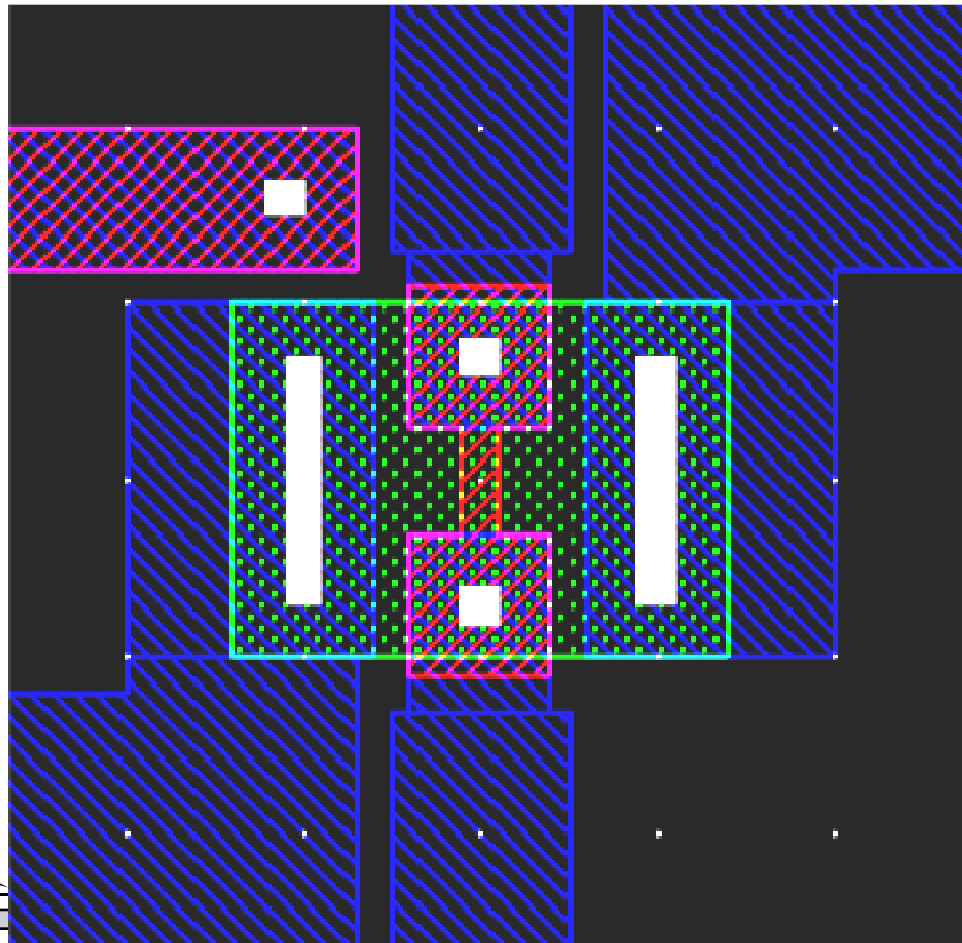
OBJECTIVE

The objective of this lab is to investigate integrated MEMS resistors and their applications as heaters, sensors and actuators.



4000x4000 chip
2200x2200 diaphragm

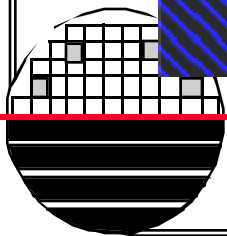
CLOSE UP OF RESISTORS AND THERMOCOUPLE



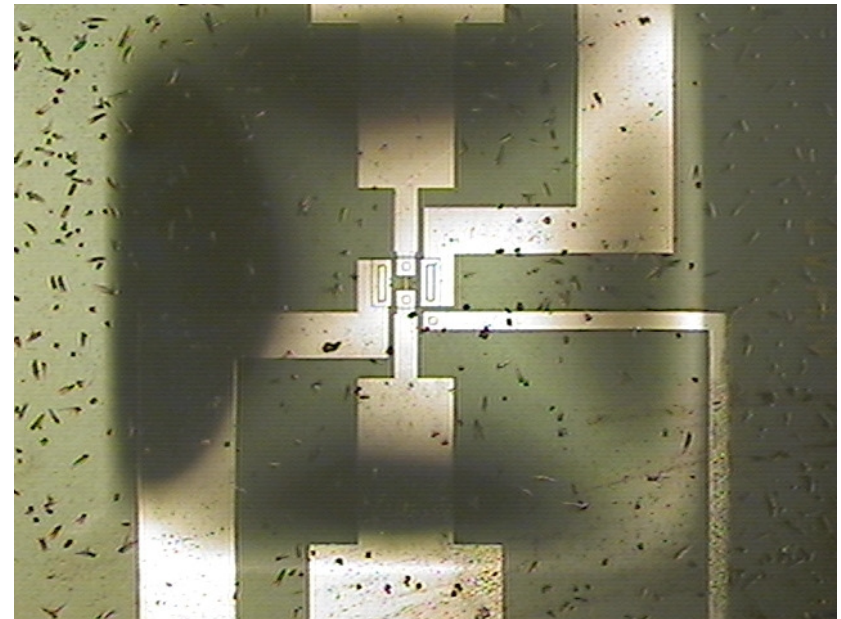
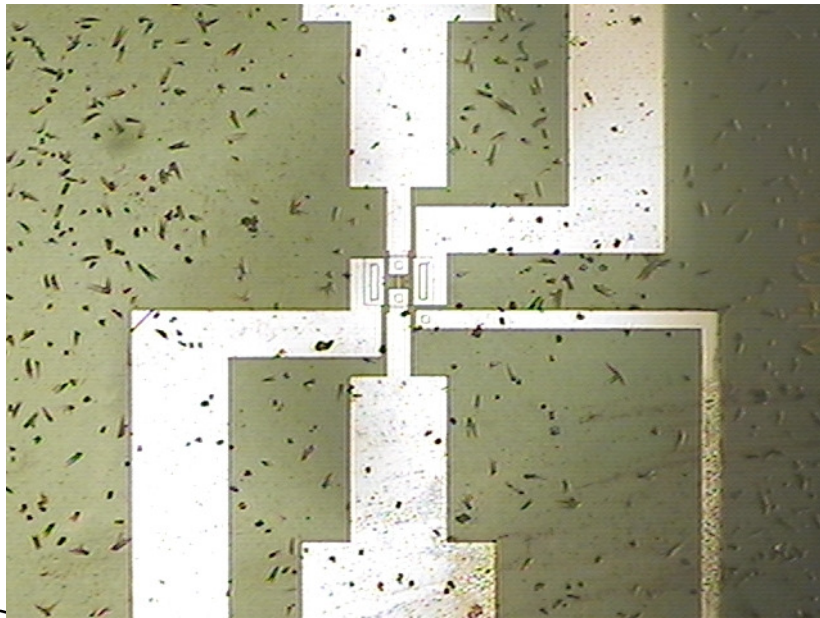
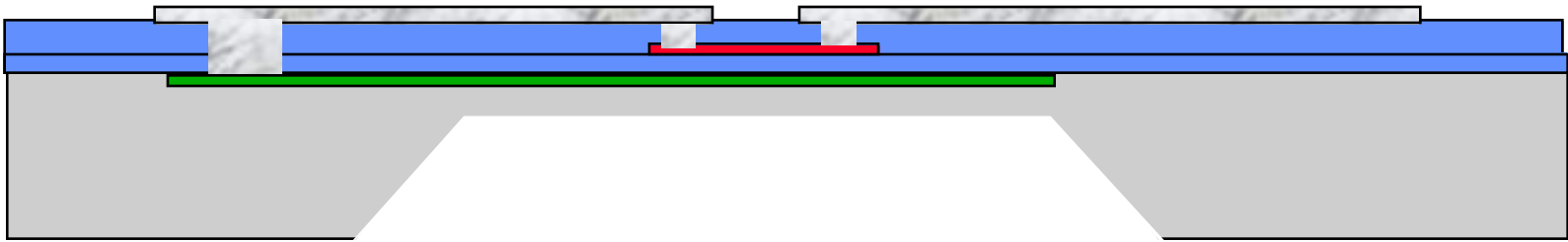
Aluminum – N+ Poly
Thermocouple

Green P+ Diffused Resistor
200 μm wide x 180 μm long

Red N+ Polysilicon Resistor
60 μm x 20 μm
+ 30 to contact so L/W ~ 6

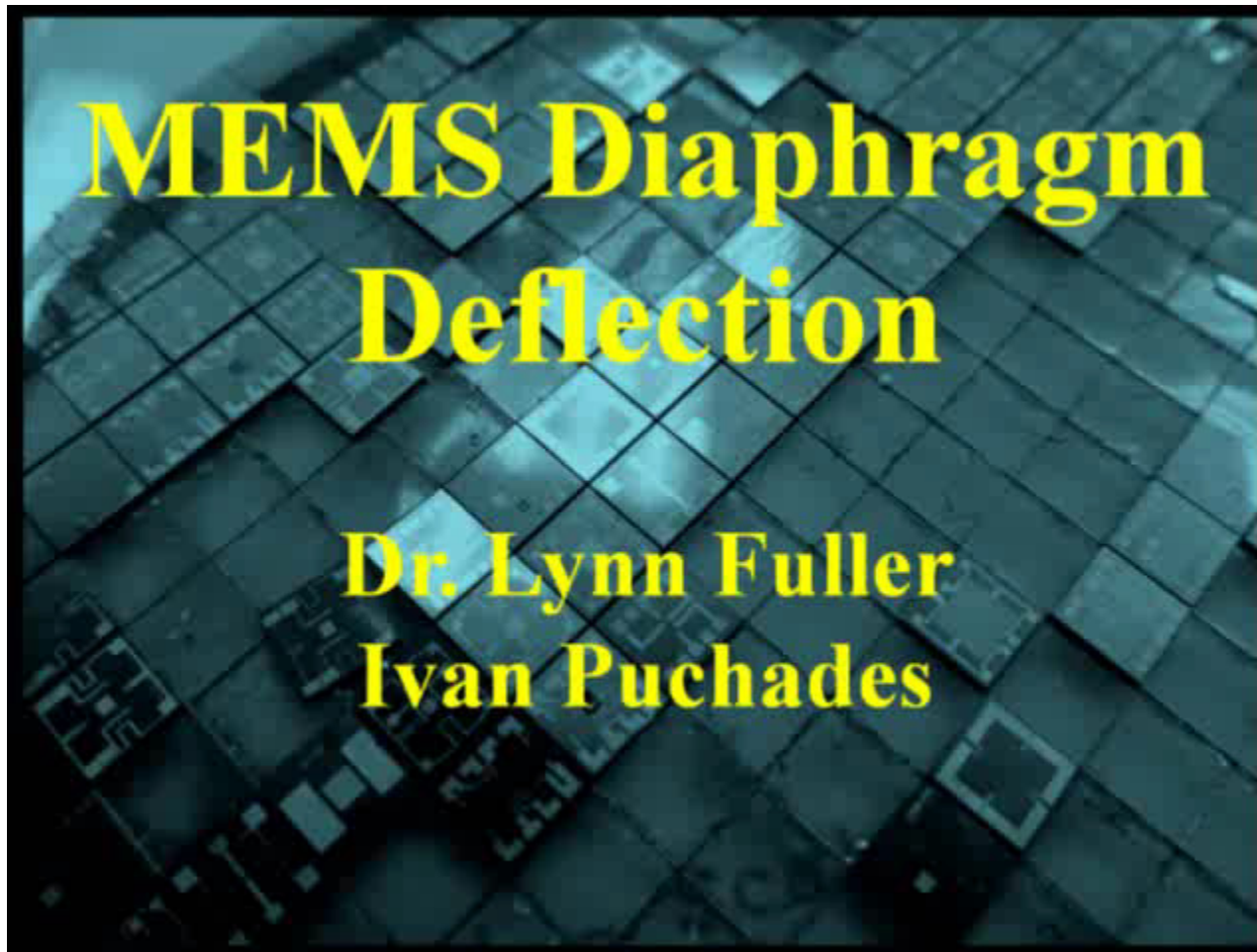


RESISTORS ON THIN DIAPHRAGM



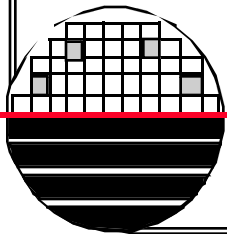
With Vacuum Chuck On

MOVIE OF DIAPHRAGM DEFLECTION

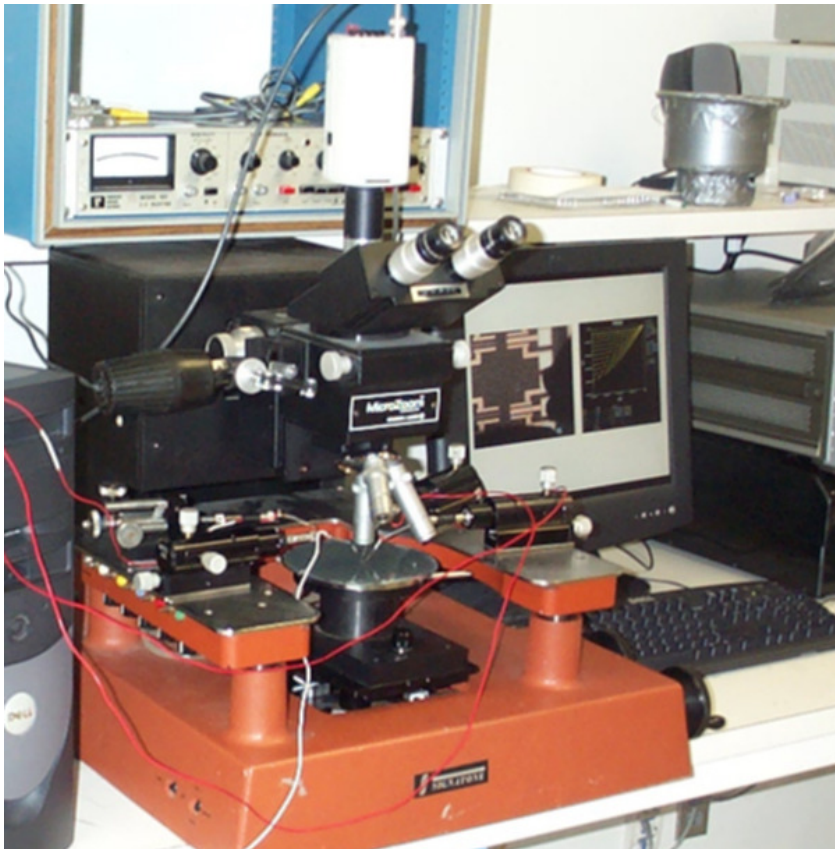


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movie click to play

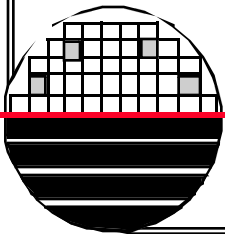


MOVIE OF PROBE STATION SET UP



Probe Station Set Up

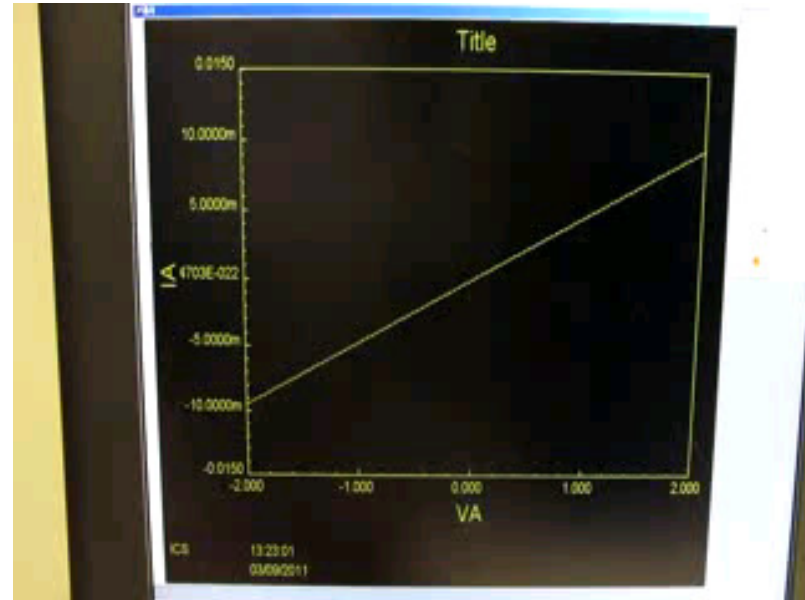
movie click to play



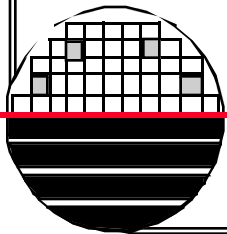
DATA COLLECTION AND RESISTANCE VALUE



movie click to play

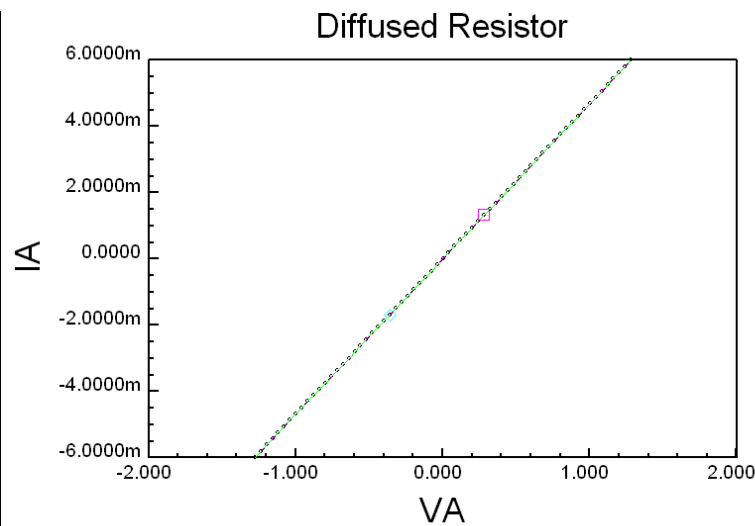


movie click to play



MEASURED RESISTANCE

Measure resistance of the heater and the sensor using the HP-4145 Semiconductor Parameter Analyzer and calculate the sheet resistance.

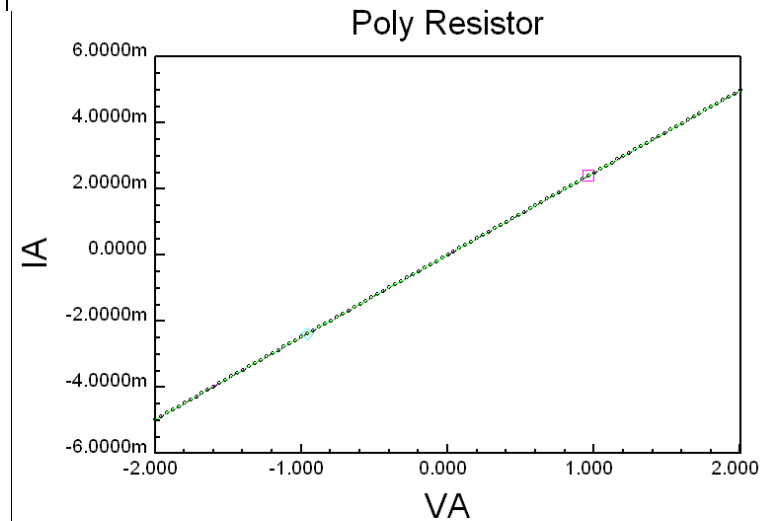


Conditions:
 Swp: SMU1
 Start: -2.00000 V
 Stop: 2.00000 V
 Step: 0.04000 V
 Pts: 101
 Con: SMU2
 Val: 0.00000 V

Fit #1:	Fit #2:	Cursors: X	Y
Type: Cursor	None	0.28000	1.31150m
Slp: 4.68750m	****	-0.36000	-1.68850m
Yint: -0.99993u	***		
Xint: 0.21332m			
ICS	13:29:40		
	03/17/2011		

Slope = 4.69m

Technology
neering



Conditions:
 Swp: SMU1
 Start: -2.00000 V
 Stop: 2.00000 V
 Step: 0.04000 V
 Pts: 101
 Con: SMU2
 Val: 0.00000 V

Fit #1:	Fit #2:	Cursors: X	Y
Type: Cursor	None	0.96000	2.39050m
Slp: 2.49036m	****	-0.96000	-2.39100m
Yint: -0.25000u	***		
Xint: 0.10041m			
ICS	13:25:17		
	03/17/2011		

Slope = 2.49m

CALCULATIONS

Using the data on the previous page calculate

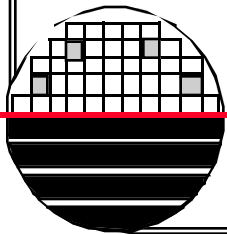
$$R = 1 / \text{slope}$$

For both diffused and poly resistors.

Calculate Rhos

$$R = \text{Rhos } L/W$$

For both diffused and poly resistors.



SEEBECK EFFECT

When two dissimilar conductors are connected together a voltage may be generated if the junction is at a temperature different from the temperature at the other end of the conductors (cold junction). This is the principal behind the thermocouple and is called the Seebeck effect.

$$\Delta V = \alpha_1(T_{\text{cold}} - T_{\text{hot}}) + \alpha_2(T_{\text{hot}} - T_{\text{cold}}) = (\alpha_1 - \alpha_2)(T_{\text{hot}} - T_{\text{cold}})$$

Where α_1 and α_2 are the Seebeck coefficients for materials 1 and 2

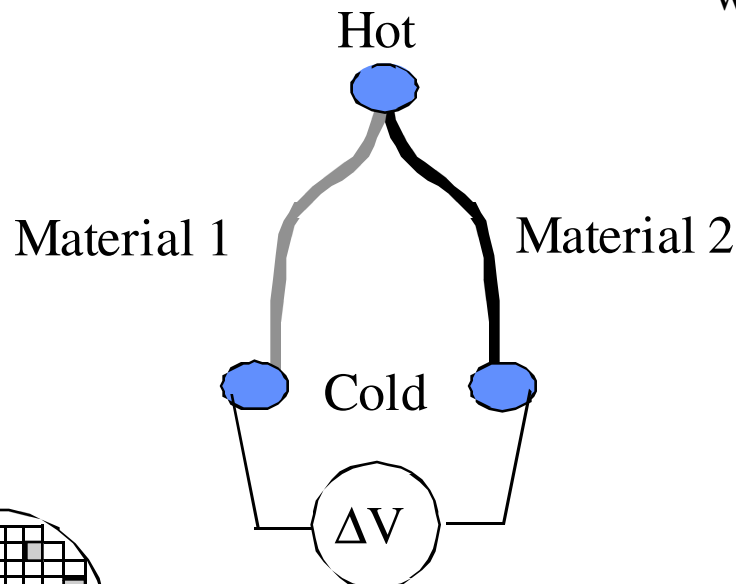


Table 2.6 The Seebeck Coefficients Relative to Platinum for Selected Metals and for *n*- and *p*-Type Polysilicon

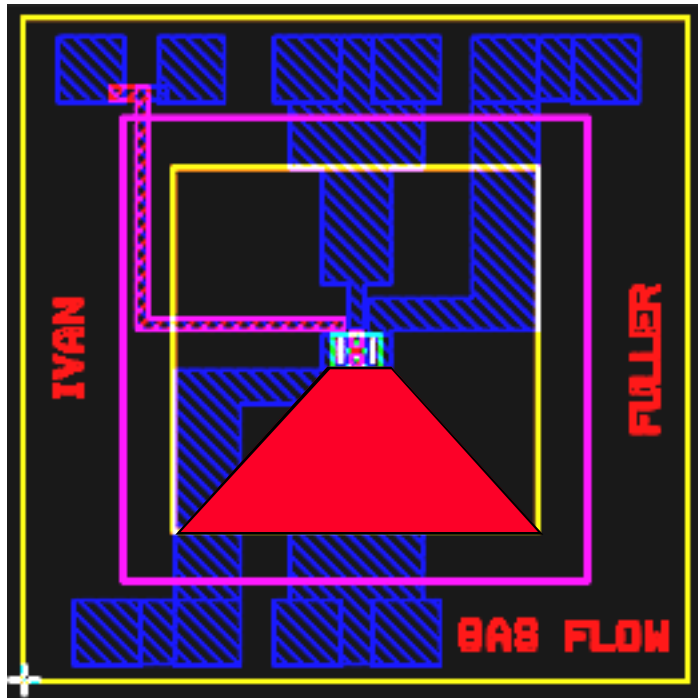
	$\mu\text{V/K}$		$\mu\text{V/K}$
Bi	-73.4	Ag	7.4
Ni	-14.8	Cu	7.6
Pa	-5.7	Zn	7.6
Pt	0	Au	7.8
Ta	3.3	W	11.2
Al	4.2	Mo	14.5
Sn	4.2	<i>n</i> -poly (30 Ω/\square)	-100
Mg	4.4	<i>n</i> -poly (2600 Ω/\square)	-450
Ir	6.5	<i>p</i> -poly (400 Ω/\square)	270

Note: The sheet resistance is given for the 0.38- μm -thick polysilicon films. Polysilicon is an attractive material for the fabrication of thermocouples and thermopiles because of its large Seebeck coefficient.

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Nadim Maluf, Kirt Williams, An Introduction to
Microelectromechanical Systems Engineering, 2nd Ed. 2004

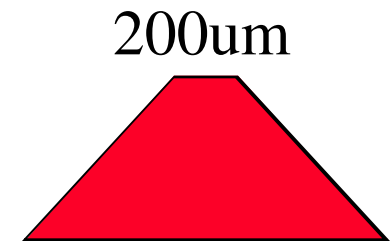
THERMAL RESISTANCE



$$R_{th} = 1/C \cdot L/Area$$

where

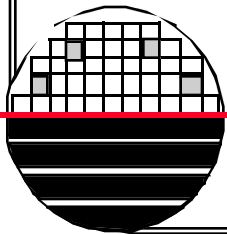
C=thermal conductivity
 L=length of thermal path between heater and ambient
 Area = cross sectional area of the path to ambient



2200 um

Thickness ~ 30 um

$R_{th} \sim 1/1.5 \cdot 1000/(500 \times 30) = 444^\circ\text{C/watt}$
 but 4 paths in parallel gives $\sim 111^\circ\text{C/watt}$



THERMAL PROPERTIES OF SOME MATERIALS

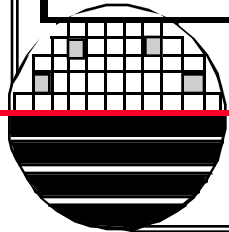
	MP °C	Coefficient of Thermal Expansion ppm/°C	Thermal Conductivity w/cmK	Specific Heat cal/gm°C
Diamond		1.0	20	
Single Crystal Silicon	1412	2.33	1.5	
Poly Silicon	1412	2.33	1.5	
Silicon Dioxide	1700	0.55	0.014	
Silicon Nitride	1900	0.8	0.185	
Aluminum	660	22	2.36	0.215
Nickel	1453	13.5	0.90	0.107
Chrome	1890	5.1	0.90	0.03
Copper	1357	16.1	3.98	0.092
Gold	1062	14.2	0.032	
Tungsten	3370	4.5	1.78	
Titanium	1660	8.9	0.17	
Tantalum	2996	6.5	0.54	
Air			0.00026	0.24
Water	0		0.0061	1.00

COLLECT DATA VERSUS HEATER VOLTAGE

Heater Voltage, V	Heater Current, I mA	Poly Heater Power W	Poly Heater Resistance Ohms	TC Voltage V mV	Temp. from TC Voltage °C	Diffused Sensor Resistance, ohms
0	0		-	.001		207
2	5			.067		210
4	10			.237		214
6	15			.517		218
8	20			1.006		220
10	25			1.690		230
12	30			2.580		340
14	35			3.500		255

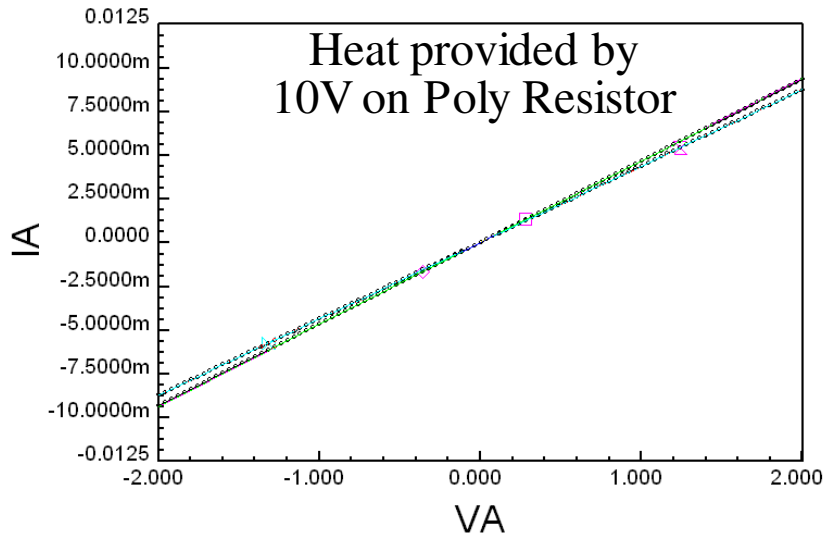
Calculations: $P = I V$

$$\text{Temp} = 25^{\circ}\text{C} + \text{TC voltage} / (\alpha_1 - \alpha_2)$$

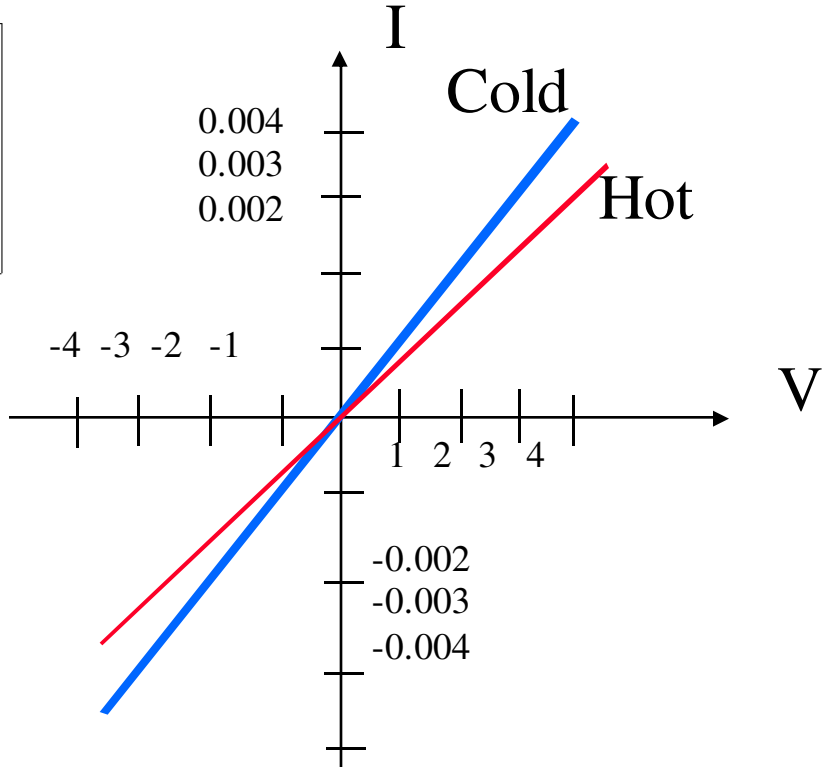


RESISTOR TEMPERATURE RESPONSE

Diffused Resistor Fit#1 Cold Fit#2 Hot-10V



Conditions:
 Swp: SMU1
 Start: -2.00000 V
 Stop: 2.00000 V
 Step: 0.04000 V
 Pts: 101
 Con: SMU2
 Val: 0.00000 V



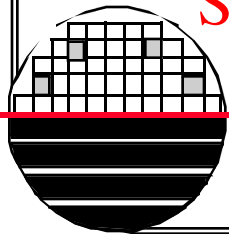
Fit #1:	Fit #2:	Cursors: X	Y
Type: Cursor	Type: Cursor	<input type="checkbox"/> 0.28000	1.31150m
Slp: 4.68750m	Slp: 4.36871m	<input type="checkbox"/> -0.36000	-1.68850m
Yint: -0.99993	Yint: 3.69883u	<input type="checkbox"/> 1.24000	5.42090m
Xint: 0.21332m	Xint: -0.84666m	<input checked="" type="checkbox"/> -1.32000	-5.76300m
ICS	13:38:47	<input type="checkbox"/> 1.24000	5.42090m
	03/17/2011	<input type="checkbox"/> -1.32000	-5.76300m

Slope = 4.37m
 Slope = 4.69m

$$R = \rho L / (W x j) \quad \text{ohms}$$

$$\rho = 1 / (q\mu_n n + q\mu_p p)$$

L, W, xj do not change with light, μ_n and μ_p does not change with light but can change with temperature, n and p does not change much in heavy doped semiconductors (that is, n and p is determined by doping)



CALCULATION OF RESISTANCE

Calculation of Mobility of Single Crystal Silicon

CONSTANTS	VARIABLES	CHOICES
$T_n = T/300 \cdot 1.14$	Temp = <input type="text" value="342"/> °K	1=yes, 0=no
	Concentration from Dose / thickness, $N = \text{Dose}/t = $ <input type="text" value="6.33E+17"/> cm ⁻³	n-type <input type="text" value="0"/> p-type <input type="text" value="1"/>
Kamins, Muller and Chan; 3rd Ed., 2003, pg 33		
		mobility = $\mu = $ <input type="text" value="129"/> cm ² /(V-sec)

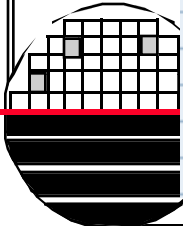
Calculation of Resistance

Length is the drawn length	Length, L = <input type="text" value="180"/> μm
Width is the drawn width	Width, W = <input type="text" value="200"/> μm
Thickness is known if poly, or Xj from Diffusion.xls	Thickness, t = <input type="text" value="3"/> μm
Implanter setting if doped by ion implant or from Diffusion.xls if doped by c	Dose = <input type="text" value="1.90E+14"/> /cm ²
	Poly ? <input type="text" value="0"/> Yes=1, No =0
	resistance/poly grain boundary <input type="text" value="0.9"/> ohm

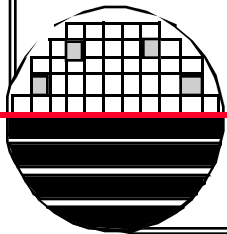
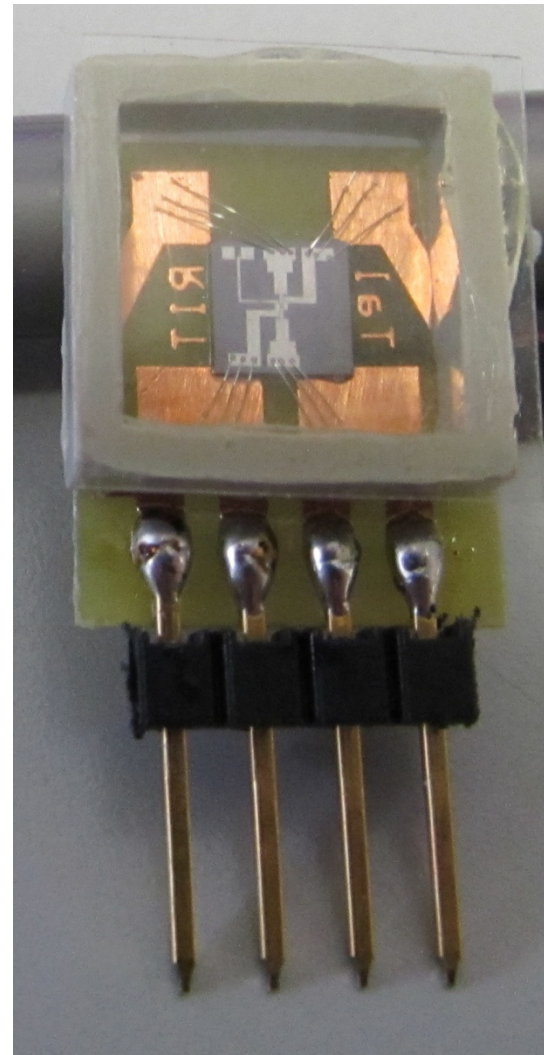
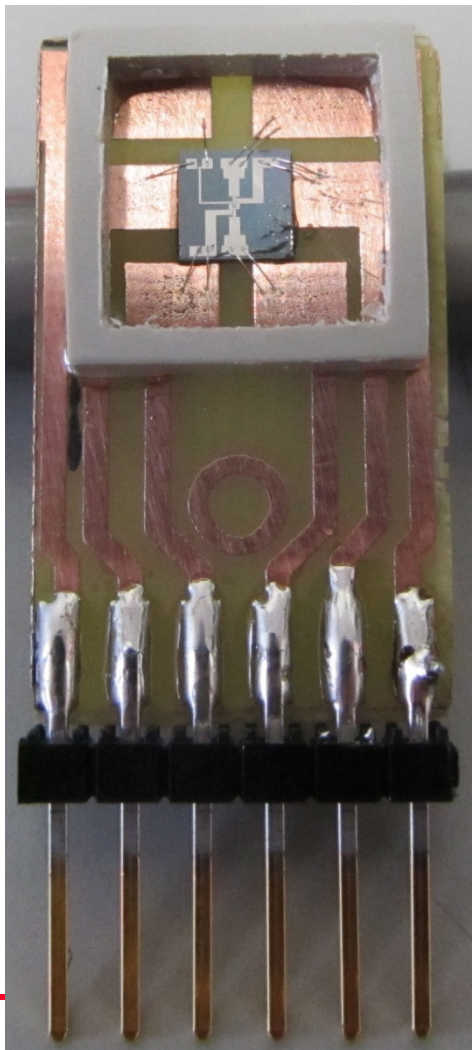
Calculation of Resistance

	approximate number of grain boundaries in path = $L / t = $ <input type="text" value="60"/>
	Average Doping = Dose/Thickness = <input type="text" value="6.33E+17"/> atoms/cm ³
	Mobility, $\mu = $ <input type="text" value="129"/> cm ² /v-sec
$q = 1.6e-19$ coulomb / ion	Rhos = sheet resistance = $1/(q \mu \text{Dose}) = $ <input type="text" value="254"/> ohms/sq
$R = \text{Rho } L / W / t$	Rho = bulk resistivity = <input type="text" value="85"/> ohm-cm
$R = \text{Rhos } L / W$	Resistance = <input type="text" value="229"/> ohms
	If Poly the effective sheet resistance = <input type="text" value="254"/> ohms/sq

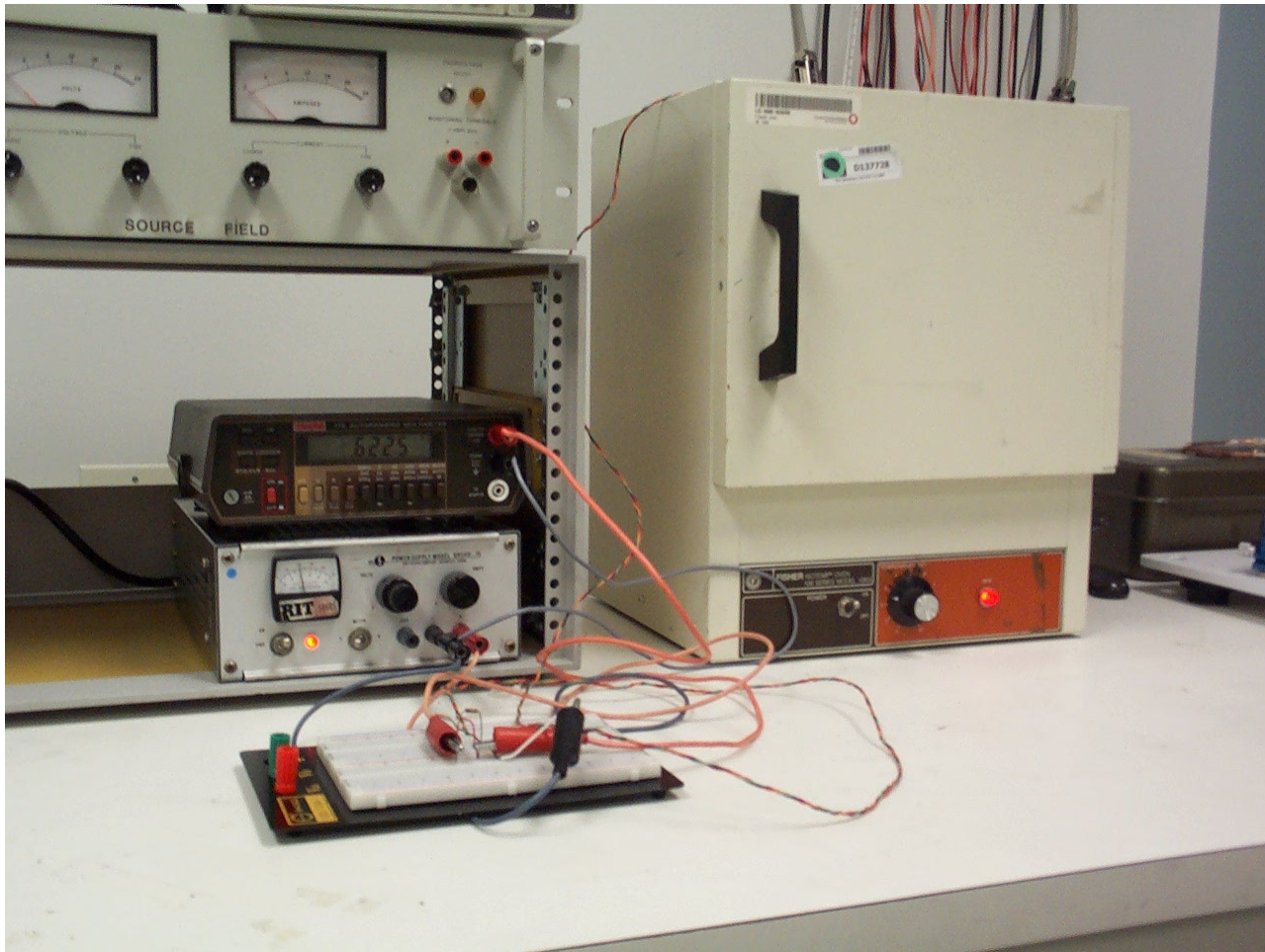
We assume the grain size is equal to the poly film thickness/2. We calculate the number of grains from the length, L, divided by the grain size, t/2. We also assume the grain boundary adds a fixed resistance that is not a function of temperature or doping. The resistance of a grain boundary is found from resistance measurements of poly resistors.



PACKAGED SENSOR CHIPS

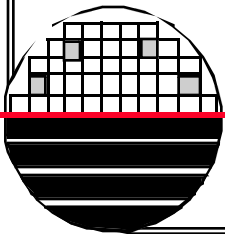


RESISTOR VS TEMPERATURE CALIBRATION



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Take data for room T up to 100°C

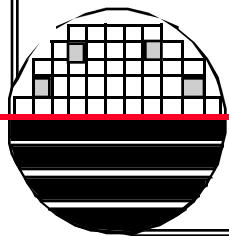
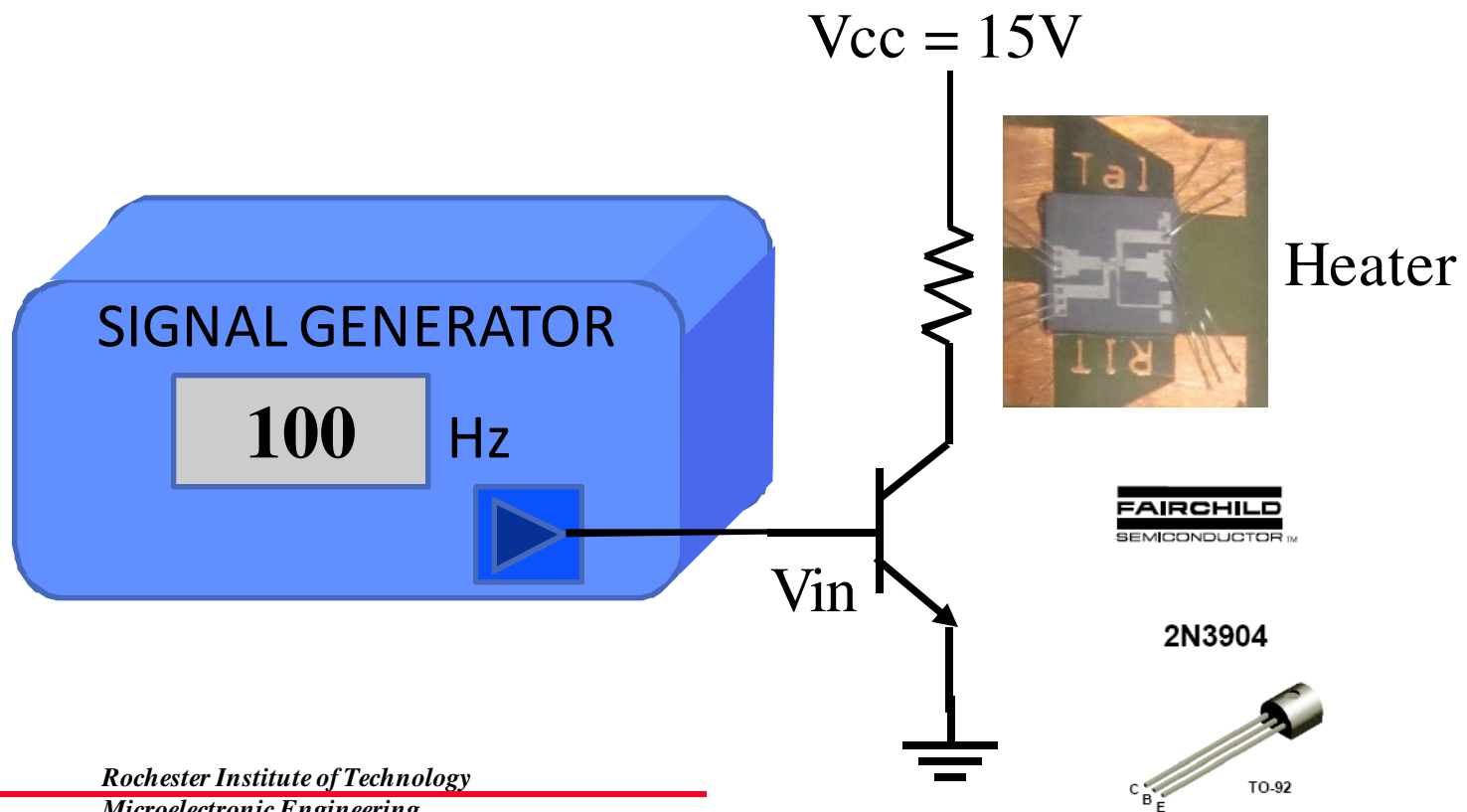


TEMPERATURE CALIBRATION DATA

Oven Temperature ° C	Poly Resistance Ohms		Diffused Resistance Ohms	
	Measured	Calculated	Measured	Calculated
30	394		207	
35	394		209	
40	394		211	
45	395		215	
50	395		218	
55	395		221	
60	395		224	
65	395		227	
70	396		230	
75	396		232	
80	396		235	
85	396		237	
90	397		240	
95	397		243	
100	397		245	

ACTUATOR CHARACTERIZATION

Supply heater voltage from a signal generator and try to evaluate the speed of response of the diaphragm movement.

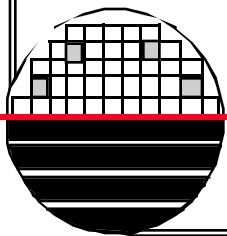
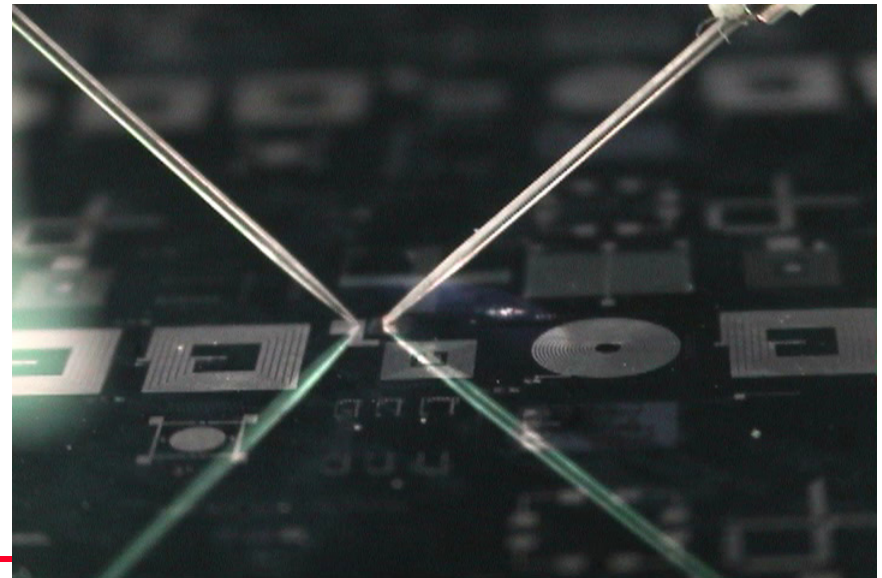


SEE IT MOVE – HEAR IT



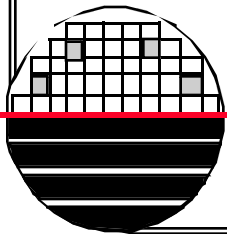
movie click to play

movie click to play



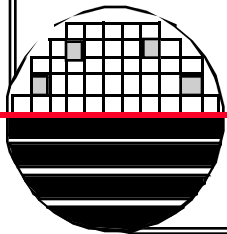
REFERENCES

1. Handbook of Modern Sensors, Jacob Faraden, Springer
2. Dr. Fuller's webpages, <http://people.rit.edu/lffeee>



HOMEWORK

1. Do a more exact calculation of the thermal resistance of the diaphragm shown on page 12.
2. Why can't we calibrate the thermocouple using the oven?
3. Does our data show a square law relationship for temperature vs. voltage to the heater? Why?
4. Plot the data and calculations from page 19. What conclusions can be made?
5. Compare heater and sensor resistance vs. temperature data from page 14 to that from page 19.
6. Discuss the theoretical frequency response of the diaphragm.
7. Write a ~150 word abstract for this lab project.



INSTRUCTORS CHECK LIST

Show MEMS chip

Take Picture

Apply Vacuum

Take Picture

Measure Heater Resistance using HP4145

Measure Sensor Resistance using HP4145

Measure Sensor Resistance with and without light

Measure Heater Resistor with voltmeter and current meter

Measure Heater I and V at 50 mV applied (no self heating)

Measure Heater I and V at 15 V applied (self heating ~1/4watt)

Take picture of diaphragm deflection due to heating

Take data for table

Take data for Sensor Resistor in oven

Take data for Heater Resistor in oven

Evaluate frequency response of heat driven diaphragm movement

